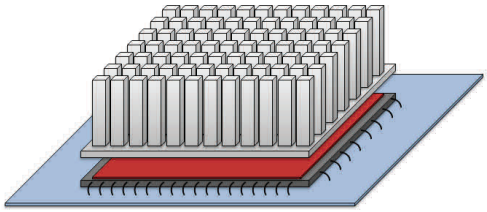

cool new technology from MAST TECHNOLOGIES

Suppress-n-Sink™

Dual Use RF Absorber + Thermal Pad

Suppress-n-Sink™ 300

MAST Technologies Suppress-n-Sink™ 300 materials are a new set of advanced dual purpose materials to be used for EMI/RF suppression and thermal conductance. The materials are formulated for high thermal conductivity as well as EMI/RF attenuation across a broad frequency range. The high thermal conductivity enables designers to mount this material directly on top of a silicon chip for heat transfer while also suppressing electromagnetic energy.

APPLICATIONS

- Suppress EMI from noisy chips
- Thermal Gap Pad
- Thermal Interface Material
- Sinking Hot Processor Chips to Heat Sinks
- Sinking Hot VGA Chips to Heat Sinks

FEATURES & BENEFITS

- Dual Use EMI and Thermal Pad
- Extremely soft for high low thermal resistance
- EMI absorption from 50 MHz to 4 GHz
- Broad Operating Temperature Range
- Wide range of thicknesses available

PART NUMBERING: MS32-XXXX-XX

Standard Part #	Thickness (inch/mm)	Frequency (GHz)
MS32-0001-00	0.020”/0.5	0.8 to 4
MS32-0002-00	0.040”/1.0	0.5 to 4
MS32-0003-00	0.060”/1.5	0.2 to 4
MS32-0004-00	0.080”/2.0	0.05 to 4

AVAILABILITY

Standard Sheet Sizes: 8.25" x 11.5" (210 x 292mm)
Other sheets sizes under development

Format: Sheets, Die Cut, Kiss Cut Pads

TYPICAL PROPERTIES

	Value	Test Method
Thickness (inches)	0.020” to 0.125”	
Thermal Conductivity (W/mK)	1.5	ASTM D5470
RF Absorption (power loss, %)	25% @ 1 GHz	
Hardness (Shore A)	24	ASTM D2240
Tensile Strength (Mpa)	>29	ASTM D412
Operating Temp. (°F)	-60 to 375	
Volume Resistivity (Ω—cm)	$>10^{10}$	ASTM D991

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